



REV.	ECN NO.	REVISED	DATE

NOTE:

1.MATERIAL:

a.HOUSING:LCP

b.CONTACT: BRASS

(SURFACE PLATING:HALF GOLD TIN)

SEE ORDERING INFORMATION

2.ELECTRIC:

a.CONTACT RESISTANCE: 100 MILLIOHMS MAX

b.INSULATION RESISTANCE: 100 MEGA OHMS MIN

c.DIELECTNIC VOLTAGE: 500V AC ONE MINUTE

d.OPERATING TEMPERATURE: -25°C~ +85°C

ORDERING INFORMATION

BS-01-A4CAK004

电池座系列

BS-01系列

DIP 90° TYPE

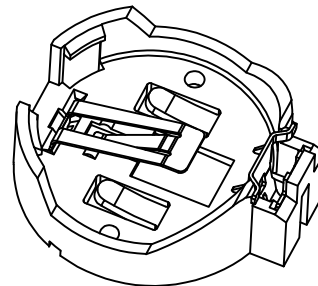
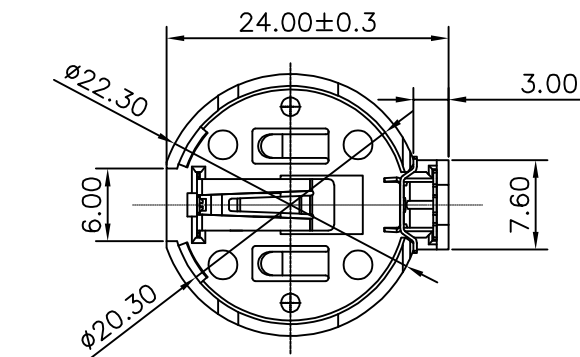
PLATING:
A-Au-PLATING
J-Ni-PLATING
K-Sn-PLATING
AK-HALF GOLD TIN

MATERIAL:
4C-LCP BLACKHF

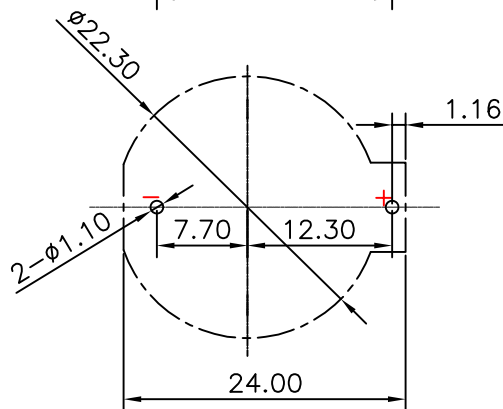
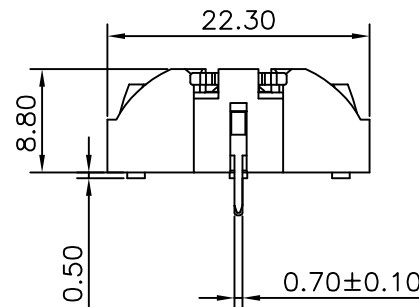
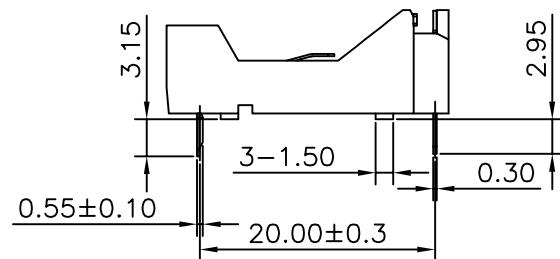
工程部

2021-04-23

H. WANG



3D



PCB Layout Diagram
Top View

3	TERMINAL(-)	1	BRASS, T=0.20mm	HALF GOLD TIN
2	TERMINAL(+)	1	BRASS, T=0.30mm	HALF GOLD TIN
1	HOUSING	1	LCP	BLACKHF
NO.	PART NAME	Q'TY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES		MYOUNG 美阳 www.meiyangdz.com					
DECIMALS: X :±0.30 X.X :±0.25 X.XX :±0.20 X.XXX :±0.10	ANGLES: X :±1° X.X :±0.5°	DSND	WangHeng	DATE	2021-04-23	TITLE:	
		CHKD	ZhouRuicai	DATE	2021-04-23	BS-2032-1-1 LCP DIP半金锡	
		APVD	XueShunyong	DATE	2021-04-23	PART NO.:	
						BS-01-A4CAK004	
WEIGHT:		SCALE: 1:1	SIZE: A4	VIEW:			
SHEET 1 OF 1		UNIT: mm	REV.: A/0	OBJECT: MY		DRAW NO.:WD-CP-0143	